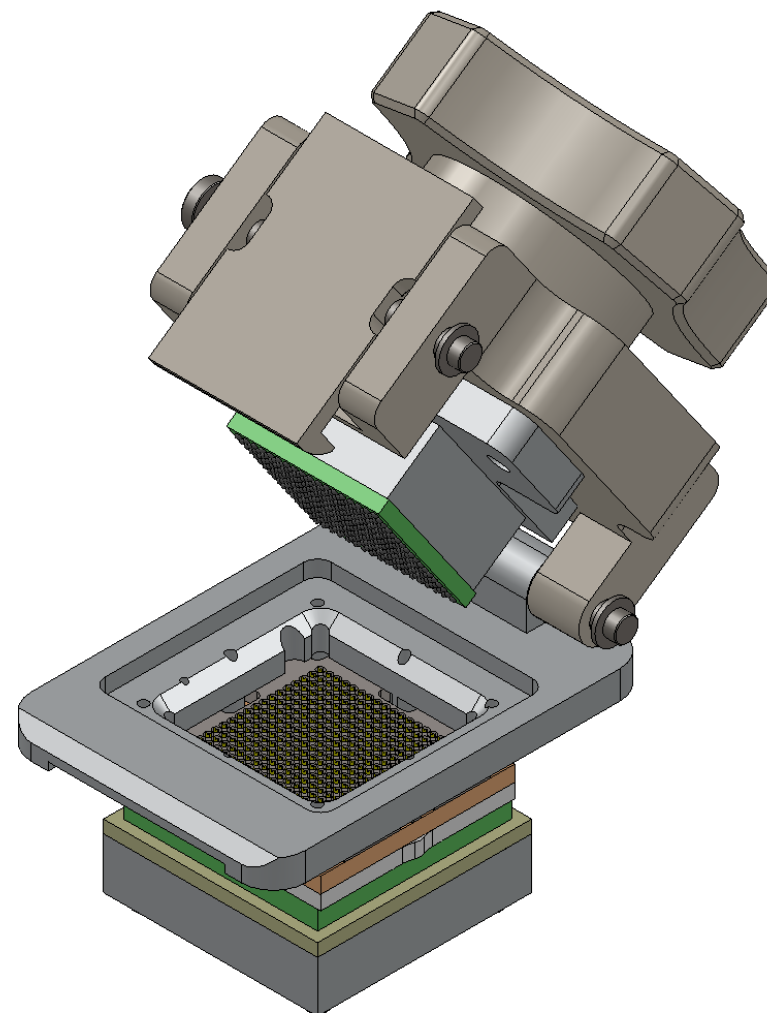
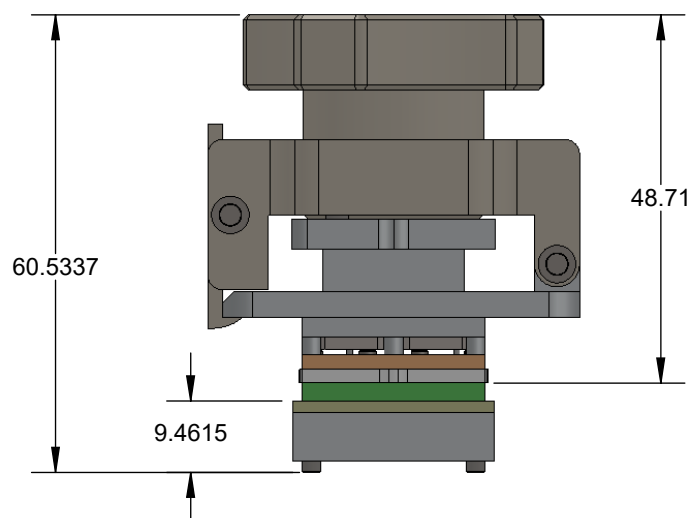
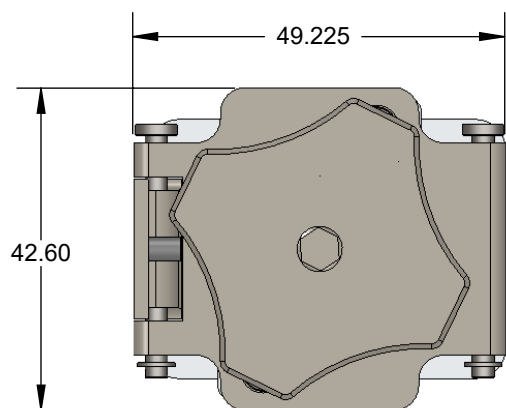


SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS

FEATURES:


- Wide temperature range (-55C to +180C)
- High current capability (up to 8A)
- Excellent signal integrity at high frequencies
- Low and stable contact resistance for reliable production yield
- Highly compliant to accommodate wide co-planarity variations
- Automated probe manufacturing enables low cost and short lead time



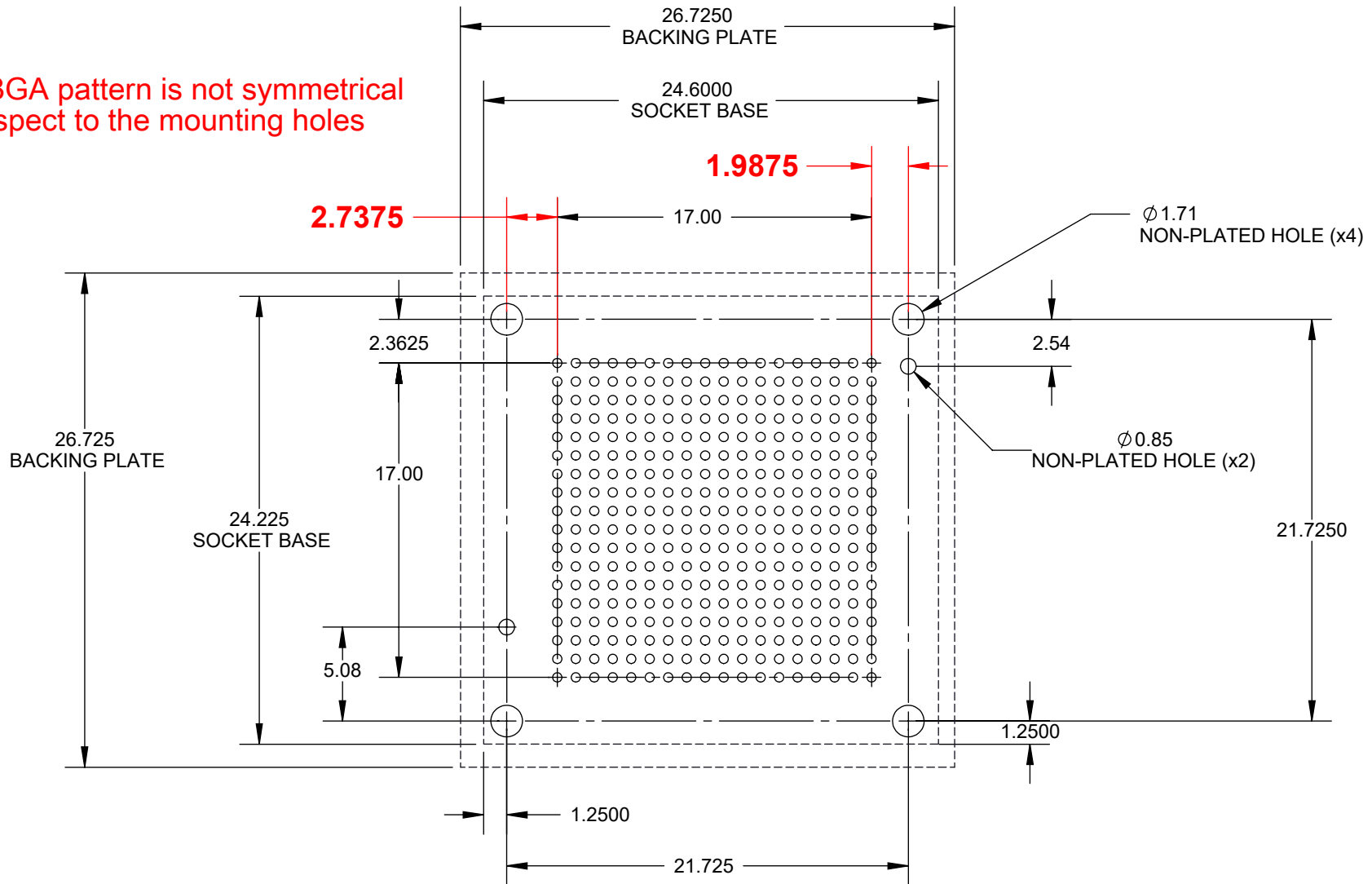
Description: Socket Specification

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001''$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001''$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005''$] unless stated otherwise. Materials and specifications are subject to change without notice.

 CBT-BGA-6010 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 137.43	STATUS: Released	SHEET: 1 OF 4	REV. C
		DRAWN BY: E. Smolentseva	SCALE: 1:1	
		FILE: CBT-BGA-6010	DATE: 08/15/2012	

Note: BGA pattern is not symmetrical with respect to the mounting holes




Target PCB Recommendations
 Total thickness: 1.6mm min.
 Plating: Gold or Solder finish
 PCB Pad height: same or higher than solder mask

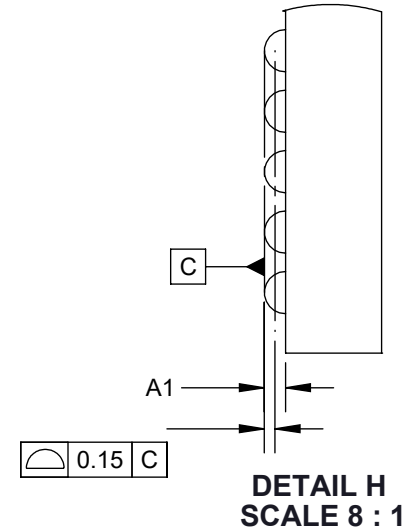
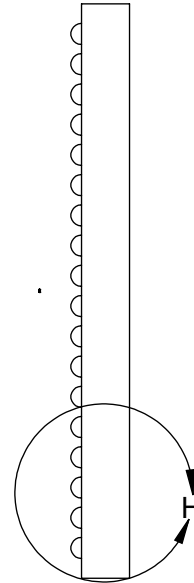
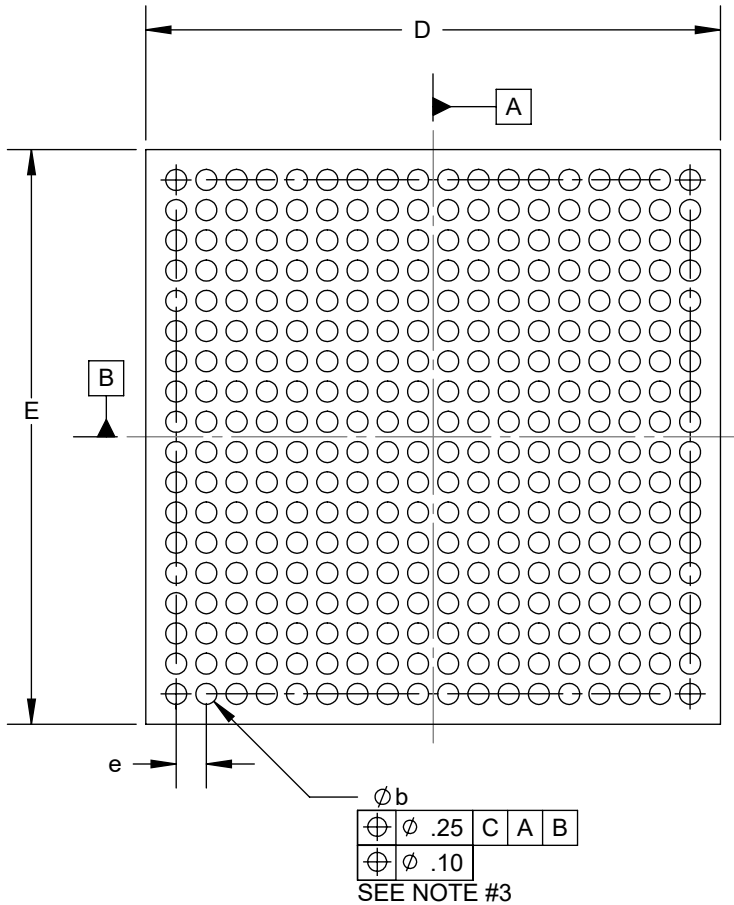
Description: Recommended PCB Layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001''$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001''$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005''$] unless stated otherwise. Materials and specifications are subject to change without notice.

 <p>CBT-BGA-6010 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	<p>Material: N/A Finish: N/A Weight: 137.43</p>	STATUS: Released	SHEET: 2 OF 4	REV. C
		DRAWN BY: E. Smolentseva	SCALE: 2:1	
		FILE: CBT-BGA-6010	DATE: 08/15/2012	

Ironwood Package C0de: BGA324G




DIM	Minimum	Maximum
A	2.2	2.7
A1	0.4	0.6
b	0.5	0.7
D	19.0 +/- 0.2mm	
E	19.0 +/- 0.2mm	
e	1.00	
ARRAY	18 x 18	
PIN COUNT	324	

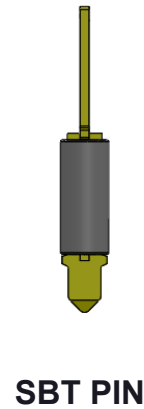
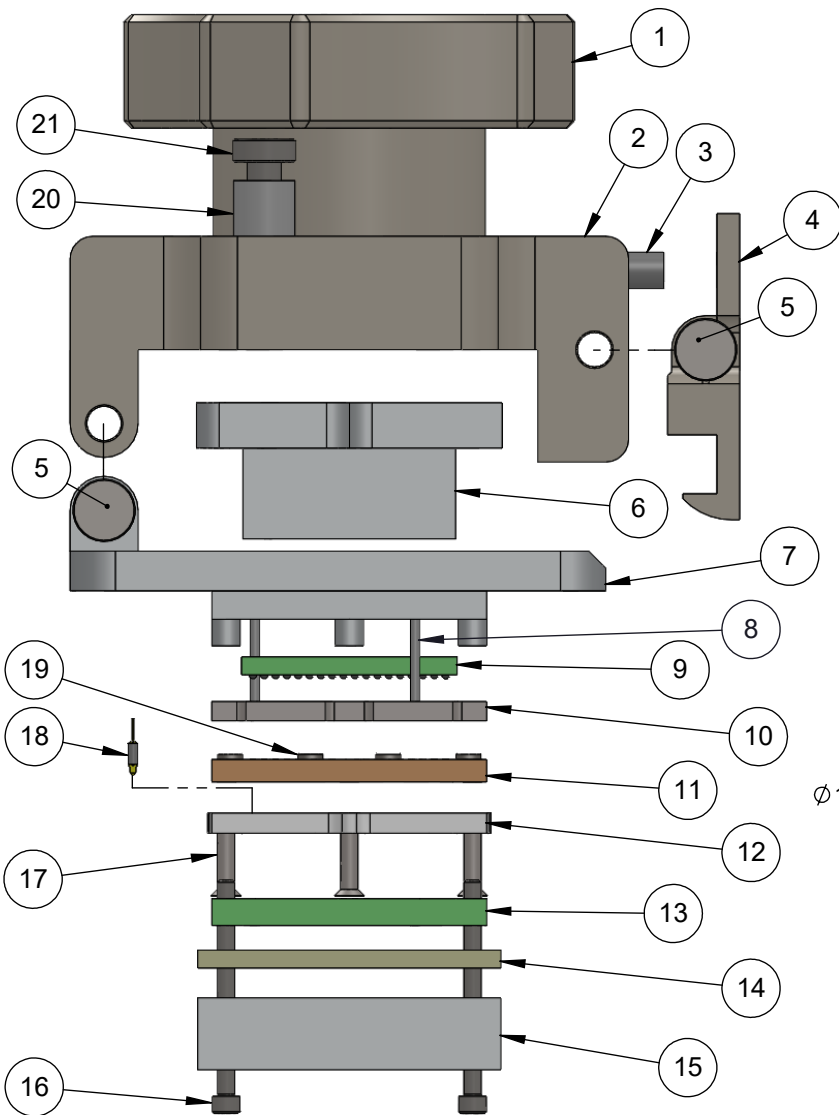
1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

Description: Compatible BGA

Primary dimension units are millimeters. Secondary dimension units are [inches]. Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001''$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001''$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005''$] unless stated otherwise. Materials and specifications are subject to change without notice.

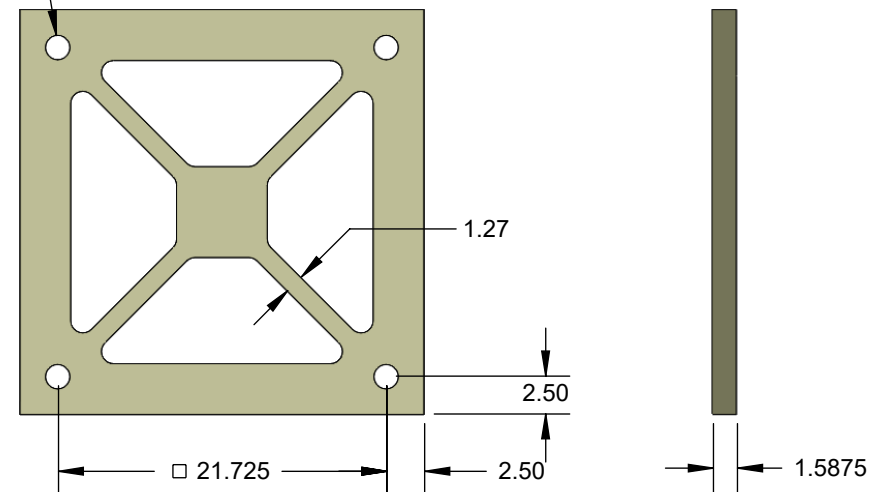
 CBT-BGA-6010 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 137.43	STATUS: Released	SHEET: 3 OF 4	REV. C
		DRAWN BY: E. Smolentseva	SCALE: 1:50	
		FILE: CBT-BGA-6010	DATE: 08/15/2012	



ITEM NO.	DESCRIPTION	QTY.
1	Compression Screw	1
2	Socket Lid	1
3	Latch Spring	1
4	Latch	1
5	Hinge Pin and Snap Ring	2
6	Compression Plate	1
7	Socket Base	1
8	Alignment Pin	2
9	Customer's IC	1
10	Floating Guide	1
11	Middle Guide	1
12	Bottom Guide	1
13	Customer's target PCB	1
14	Insulation Plate	1
15	Backing Plate	1
16	Mounting Screw	4
17	Pin Guide Screw	2
18	Spring Pin	324
19	Floating Guide Spring	8
20	Lid Spring	2
21	Lid Screw	2

Ø1.61±0.10 (x4)

Insulation Plate Specification




Rev	Date	Initials	Description
A	08/15/12	ELS	Original
B	12/06/12	DH	Changed M2816 to M1308, and Changed M2815 to M1302
C	11/18/15	JV	Updated pin guides, and pin guide screw to current design standards

Description: Socket Assy, Insulation Plate

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

 <p>CBT-BGA-6010 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	<p>Material: N/A Finish: N/A Weight: 137.43</p>	<p>STATUS: Released</p>	<p>SHEET: 4 OF 4</p>	<p>REV. C</p>
		<p>DRAWN BY: E. Smolentseva</p>	<p>SCALE: 1:1</p>	
		<p>FILE: CBT-BGA-6010</p>	<p>DATE: 08/15/2012</p>	